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CLAIMS

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1. A module component comprising:
a substrate made of resin having a penetration hole;
a circuit wiring disposed on both sides of said substrate; and
5 a chip component having a height almost same as a depth of said penetration hole and put in the penetration hole for electrically coupling said circuit wiring disposed on both sides of said substrate, wherein the penetration hole is formed according to a specified rule, and wherein a chip component having a specific value is accommodated to
10 compose a desired circuit.
2. A module component according to claim 1, wherein the penetration hole is formed only at a specified position according to a matrix, and said chip component having the specific value is
15 accommodated to compose the desired circuit.
3. A module component according to claim 1, wherein the penetration holes are formed according to a matrix, and said chip component having the specific value is put in a specified penetration hole.
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4. A module component according to claim 1 further comprising a fixing member for filling up a gap between said chip component put in the penetration hole and the penetration hole.
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5. A module component according to claim 1, wherein the penetration hole is tapered.
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6. A module component according to claim 1, wherein support means is formed at the penetration hole for supporting said chip component.

5 7. A module component according to claim 1 further comprising an auxiliary substrate disposed at least over one of the both sides of said substrate.

10 8. A module component according to claim 1 further comprising first and second auxiliary substrates disposed with holding said substrate therebetween, wherein a desired circuit is composed by employing a chip component of a specified height being greater than the depth of the penetration hole and not projecting from said first and second auxiliary substrates when put in the penetration hole.

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9. A module component according to claim 1, wherein an end of said chip component and a surface of said substrate are formed in different colors.

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10. A module component according to claim 1 further comprising an IC chip mounted on an auxiliary substrate; and a capacitor put in a penetration hole immediately beneath said IC chip to be coupled directly with said IC chip.

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11. A module component according to claim 1 further comprising a ground layer disposed one of beneath said substrate and by way of an auxiliary substrate, wherein said ground layer is coupled with said circuit

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wiring disposed on a lower side of said substrate.

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12. A module component according to claim 1 further comprising:
an IC chip mounted on an auxiliary substrate; and
5 a ground layer disposed one of beneath said substrate and by way of
an auxiliary substrate,
wherein said IC chip is coupled directly with said ground layer.

13. A manufacturing method according to a module component
10 comprising the steps of:

forming a penetration hole on a substrate made of resin;

inserting a chip component into the penetration hole, the chip
component having an almost same height as a depth of the penetration
hole;

- 15 forming a circuit wiring for coupling the chip component on said
substrate; and

heating, compressing, and adhering an auxiliary substrate on at
least one of both sides of the substrate,

- wherein the penetration hole is formed according to a specified rule, and a
20 chip component of a specific value is accommodated to compose a desired
circuit.

14. A manufacturing method according to claim 13, wherein said
step of forming the penetration hole comprises forming the penetration
25 hole at a specified position according to a matrix, and a chip component of
a specific value is put in the penetration hole to compose a desired circuit.

15. A manufacturing method according to claim 13, wherein said step of forming the penetration hole comprises the step of forming the penetration holes according to a matrix, and wherein said step of inserting the chip component comprises the step of inserting the chip component of a specific value in a specified penetration hole to compose a desired circuit.

16. A module component comprising:
a molded element with a chip component molded said resin with resin, an end electrode of said chip component being exposed; and
10 a circuit wiring on at least one side of said molded elements, wherein said chip component is disposed according to a specified rule, and said chip component is molded with said resin to compose a desired circuit.

15 17. A module component according to claim 16, wherein said chip component is disposed at a specified position according to a matrix, and said chip component is molded with said resin to compose a desired circuit.

20 18. A module component according to claim 17 further comprising a dummy component having a same size as said chip component disposed at a position not filled with said chip component according to the matrix.

19. A module component according to claim 16, wherein said
25 molded element is molded with one of epoxy resin and phenol resin.

20. A module component according to claim 16, wherein said resin

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contains a filler having at least one of a high heat conductivity and heat resistance.

21. A module component according to claim 16, wherein said resin
5 contains at least one of Al_2O_3 , SiC , Al_3N_4 , and Si_3N_4 as a filler.

22. A module component according to claim 16, wherein said resin
contains at least one of ceramic powder and SiO_2 as a filler.

10 23. A module component according to claim 16, wherein said resin
contains a magnetic material.

24. A module component according to claim 16, wherein said end
electrode of said chip component and a surface of said molded element are
15 formed in different colors.

25. A module component according to claim 16, wherein said
molded element comprises a ground layer over a bottom of said molded
element, and wherein said ground layer is directly coupled with said end
20 electrode.

26. A module component comprising:
a chip component disposed according to a specified rule;
an IC chip mounted to one side of a molded element formed by
25 resin;

a circuit wiring on a substrate for directly coupling an electrode
terminal of said IC chip with said wiring patterns on said substrate

through said chip component.

27. A manufacturing method of a module component comprising:
an inserting step of inserting a chip component in a molding die;
5 a primary molding step of filling the molding die with resin with an
end electrode of the chip component exposed;
a peeling step of peeling the molding die at a side of inserting the
chip component;
a secondary molding step of filling the molding die with resin with
10 an end electrode of the chip component; and
a forming step of forming a circuit wiring on one side or both sides
of a molded element molded with resin,
wherein the chip component is disposed according to a specified rule, and
the chip component are molded with the resin to compose a desired circuit.

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28. A manufacturing method according to claim 27, wherein the
chip component is disposed in a specified position according to a matrix,
and the chip component of a specific value is molded with the resin to
compose a desired circuit.

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29. A manufacturing method according to claim 28, wherein a
dummy component having a same size as the chip component is inserted
at a position where the chip component is not inserted according to the
matrix.

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30. A manufacturing method of a module component comprising:
an inserting step of inserting a chip component in a molding die, the

a primary molding step of filling with resin with an end electrode of the chip component exposed;

5 chip component;

a step of mounting an IC chip on one side of a molded element
molded with resin and coupling an other side to a substrate,

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